

## General Description

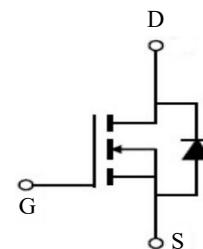
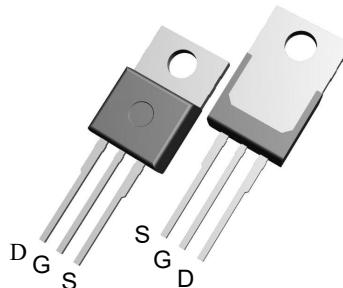
The MY120N06P is the high cell density trenched N-ch MOSFETs, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications.

The MY120N06P meet the Ro HS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.



## Features

V <sub>DSS</sub>	60	V
I <sub>D</sub>	120	A
R <sub>DS(ON)</sub> (at V <sub>GS</sub> =10V)	4	mΩ
R <sub>DS(ON)</sub> (at V <sub>GS</sub> =4.5V)	5.2	mΩ



## Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
MY120N06P	TO-220	120N06P	1000

## Absolute Maximum Ratings (Ta=25°C unless otherwise noted)

Symbol	Parameter	Value	Unit
V <sub>DSS</sub>	Drain-Source Voltage	60	V
I <sub>D</sub>	Drain Current	120	A
		70	
V <sub>GSS</sub>	Gate-Source Voltage	±25	V
E <sub>AS</sub>	Single Pulse Avalanche Energy (note1)	550	mJ
I <sub>AR</sub>	Avalanche Current (note2)	100	A
P <sub>D</sub>	Power Dissipation (Tc=25°C)	170	W
T <sub>j</sub>	Junction Temperature(Max)	175	°C
T <sub>sg</sub>	Storage Temperature	-55~+175	°C
T <sub>L</sub>	Maximum lead temperature for soldering purpose, 1/8" from case for 5 seconds	300	°C

## Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
R <sub>θJC</sub>	Thermal Resistance,Junction to Case	-	0.88	°C/W
R <sub>θJA</sub>	Thermal Resistance,Junction to Ambient	-	65	°C/W
R <sub>θCS</sub>	Thermal Resistance,Case to Sink	-	0.24	°C/W

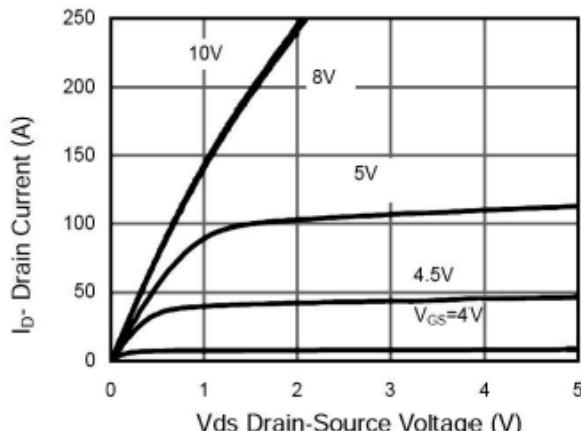
**Electrical Characteristics** at  $T_J=25^\circ\text{C}$  unless otherwise specified

Parameter	Symbol	Condition	Min	Typ	Max	Unit
<b>Off Characteristics</b>						
Drain-Source Breakdown Voltage	$\text{BV}_{\text{DSS}}$	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250\mu\text{A}$	60	65	-	V
Zero Gate Voltage Drain Current	$I_{\text{DSS}}$	$V_{\text{DS}}=60\text{V}, V_{\text{GS}}=0\text{V}$	-	-	1	$\mu\text{A}$
Gate-Body Leakage Current	$I_{\text{GSS}}$	$V_{\text{GS}}=\pm20\text{V}, V_{\text{DS}}=0\text{V}$	-	-	$\pm100$	nA
<b>On Characteristics</b> <sup>(Note 3)</sup>						
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=250\mu\text{A}$	2	3	4	V
Drain-Source On-State Resistance	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}}=10\text{V}, I_{\text{D}}=40\text{A}$	-	4.0	5.0	$\text{m}\Omega$
Forward Transconductance	$g_{\text{FS}}$	$V_{\text{DS}}=10\text{V}, I_{\text{D}}=40\text{A}$	-	50	-	S
<b>Dynamic Characteristics</b> <sup>(Note 4)</sup>						
Input Capacitance	$C_{\text{iss}}$	$V_{\text{DS}}=30\text{V}, V_{\text{GS}}=0\text{V}, F=1.0\text{MHz}$	-	4800	-	PF
Output Capacitance	$C_{\text{oss}}$		-	440	-	PF
Reverse Transfer Capacitance	$C_{\text{rss}}$		-	260	-	PF
<b>Switching Characteristics</b> <sup>(Note 4)</sup>						
Turn-on Delay Time	$t_{\text{d(on)}}$	$V_{\text{DD}}=30\text{V}, I_{\text{D}}=1\text{A}$ $V_{\text{GS}}=10\text{V}, R_{\text{GEN}}=2.5\Omega$	-	16.8	-	nS
Turn-on Rise Time	$t_r$		-	10.8	-	nS
Turn-Off Delay Time	$t_{\text{d(off)}}$		-	55	-	nS
Turn-Off Fall Time	$t_f$		-	13.6	-	nS
Total Gate Charge	$Q_g$	$V_{\text{DS}}=30\text{V}, I_{\text{D}}=30\text{A}, V_{\text{GS}}=10\text{V}$	-	85	-	nC
Gate-Source Charge	$Q_{gs}$		-	18	-	nC
Gate-Drain Charge	$Q_{gd}$		-	28	-	nC
<b>Drain-Source Diode Characteristics</b>						
Diode Forward Voltage <sup>(Note 3)</sup>	$V_{\text{SD}}$	$V_{\text{GS}}=0\text{V}, I_{\text{S}}=20\text{A}$	-	-	1.2	V
Diode Forward Current <sup>(Note 2)</sup>	$I_{\text{S}}$	-	-	-	120	A
Reverse Recovery Time	$t_{rr}$	$T_J = 25^\circ\text{C}, IF = 40\text{A}$ $di/dt = 100\text{A}/\mu\text{s}$ <sup>(Note 3)</sup>	-	38	-	nS
Reverse Recovery Charge	$Q_{rr}$		-	53	-	nC
Forward Turn-On Time	$t_{\text{on}}$	Intrinsic turn-on time is negligible (turn-on is dominated by LS+LD)				

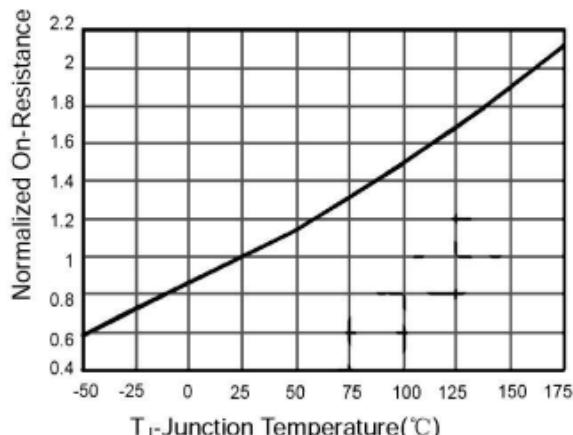
**Notes:**

1. Repetitive Rating: Pulse width limited by maximum junction temperature
2. Surface Mounted on FR4 Board,  $t \leq 10$  sec.
3. Pulse Test: Pulse Width  $\leq 300\mu\text{s}$ , Duty Cycle  $\leq 2\%$
4. Guaranteed by design, not subject to production
5. EAS condition:  $T_J=25^\circ\text{C}, V_{\text{DD}}=30\text{V}, V_G=10\text{V}, L=0.5\text{mH}, R_g=25\Omega$

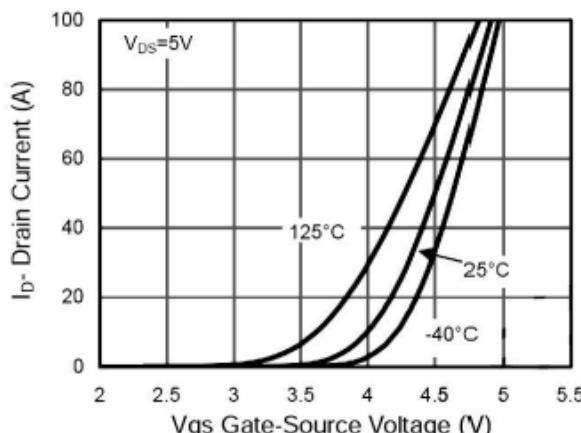
**Typical Characteristics**



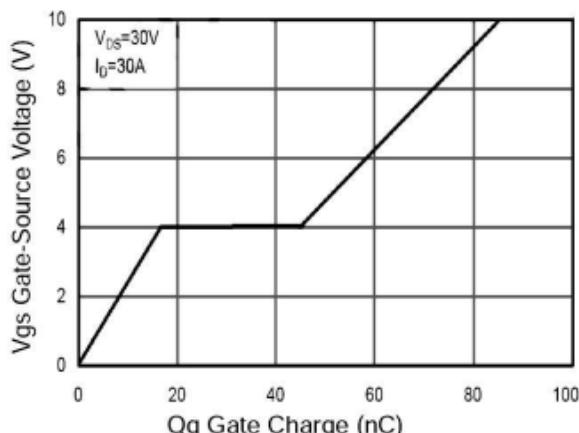
**Figure 1 Output Characteristics**



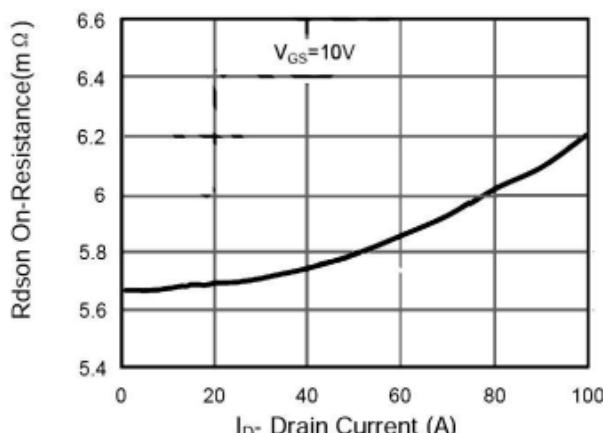
**Figure 4 Rdson-JunctionTemperature**



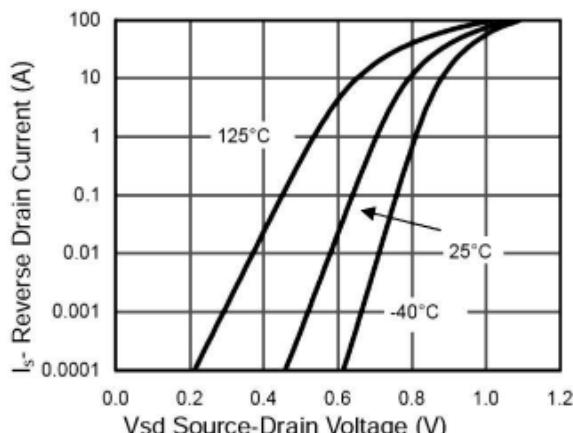
**Figure 2 Transfer Characteristics**



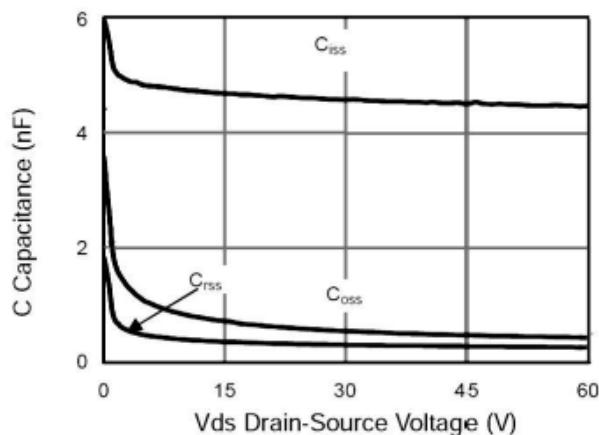
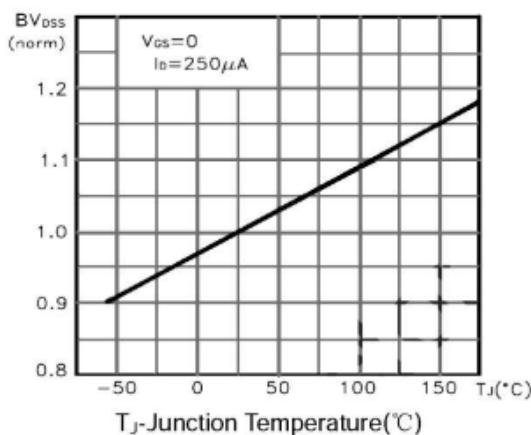
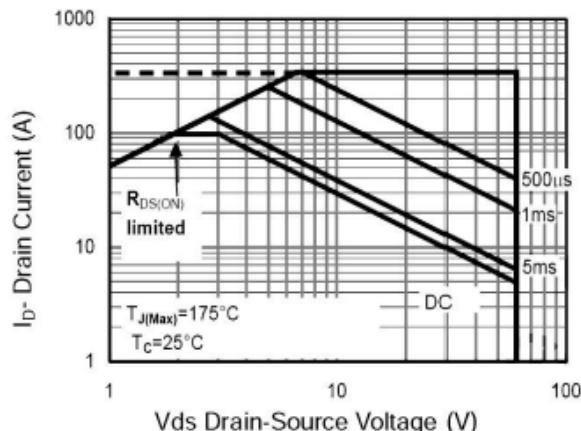
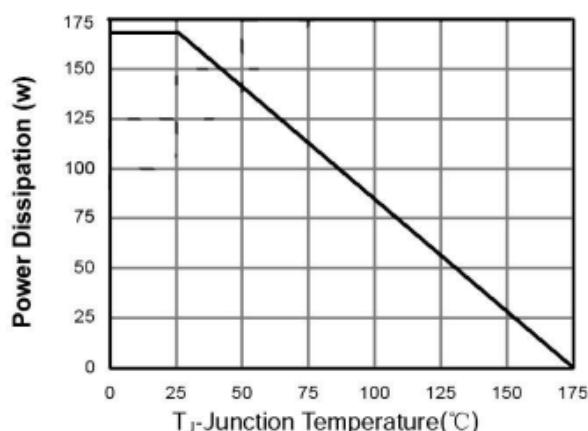
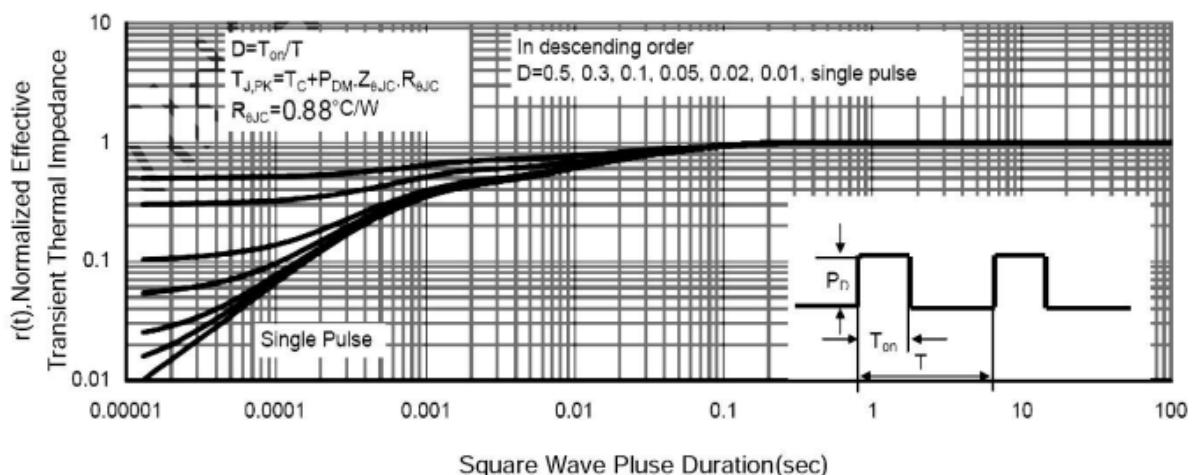
**Figure 5 Gate Charge**

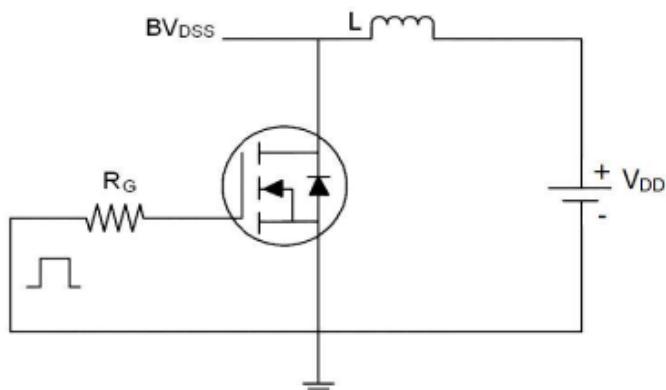
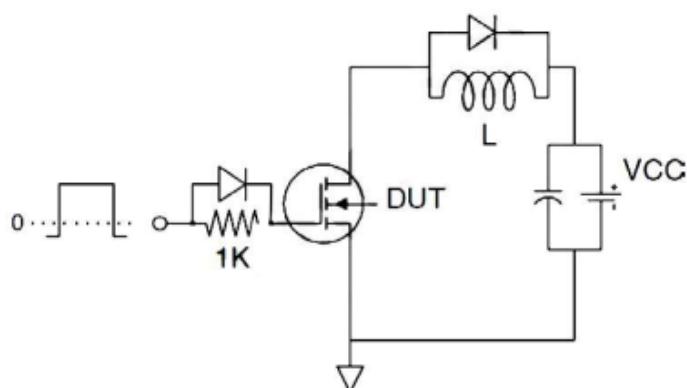
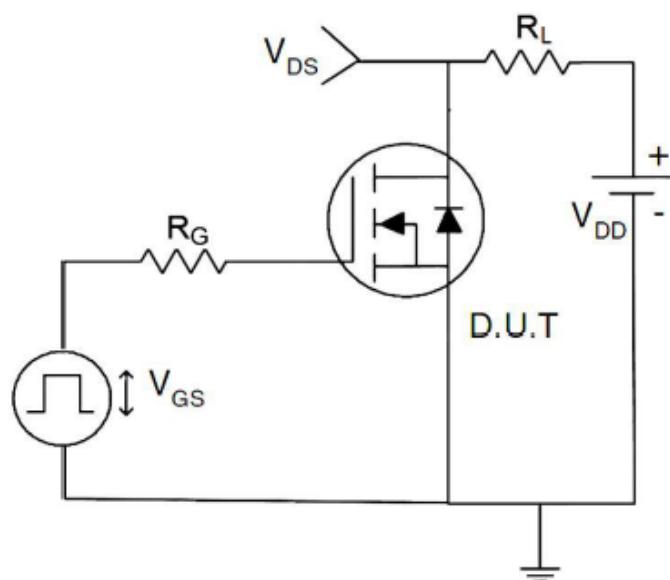


**Figure 3 Rdson- Drain Current**



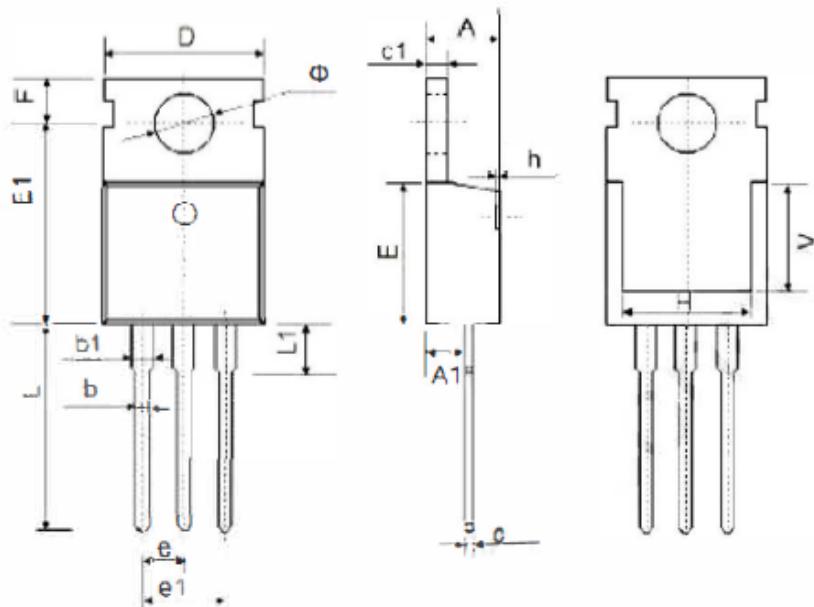
**Figure 6 Source- Drain Diode Forward**

**Figure 7 Capacitance vs Vds****Figure 9  $BV_{DSS}$  vs Junction Temperature****Figure 8 Safe Operation Area****Figure 10 Power De-rating****Figure 11 Normalized Maximum Transient Thermal Impedance**

**Test circuit****1) E<sub>AS</sub> test Circuits****2) Gate charge test Circuit:****3) Switch Time Test Circuit:**

**Package Dimension**

TO-220



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	4.30	4.80	0.169	0.189
A1	2.20	2.70	0.087	0.106
b	0.70	0.95	0.276	0.037
b1	1.10	1.50	0.043	0.059
c	0.40	0.65	0.016	0.026
c1	1.20	1.45	0.047	0.057
D	9.70	10.30	0.382	0.406
E	8.75	9.65	0.344	0.380
E1	12.50	13.10	0.492	0.516
e	2.540 Typ.		0.100 Typ.	
e1	4.98	5.18	0.196	0.204
F	2.60	3.00	0.102	0.118
H	7.00	8.40	0.276	0.331
h	0	0.3	0	0.012
L	12.75	13.90	0.502	0.547
L1	2.85	3.40	0.112	0.134
V	6.700 Ref.		0.264 Ref.	
Φ	3.50	3.80	0.138	0.150